

(6)

TI-27698

JMC

⑥ Assembly member into package

Use standard K6D/IE essay
 practices using the flip configuration
 of the K6D/IE configuration

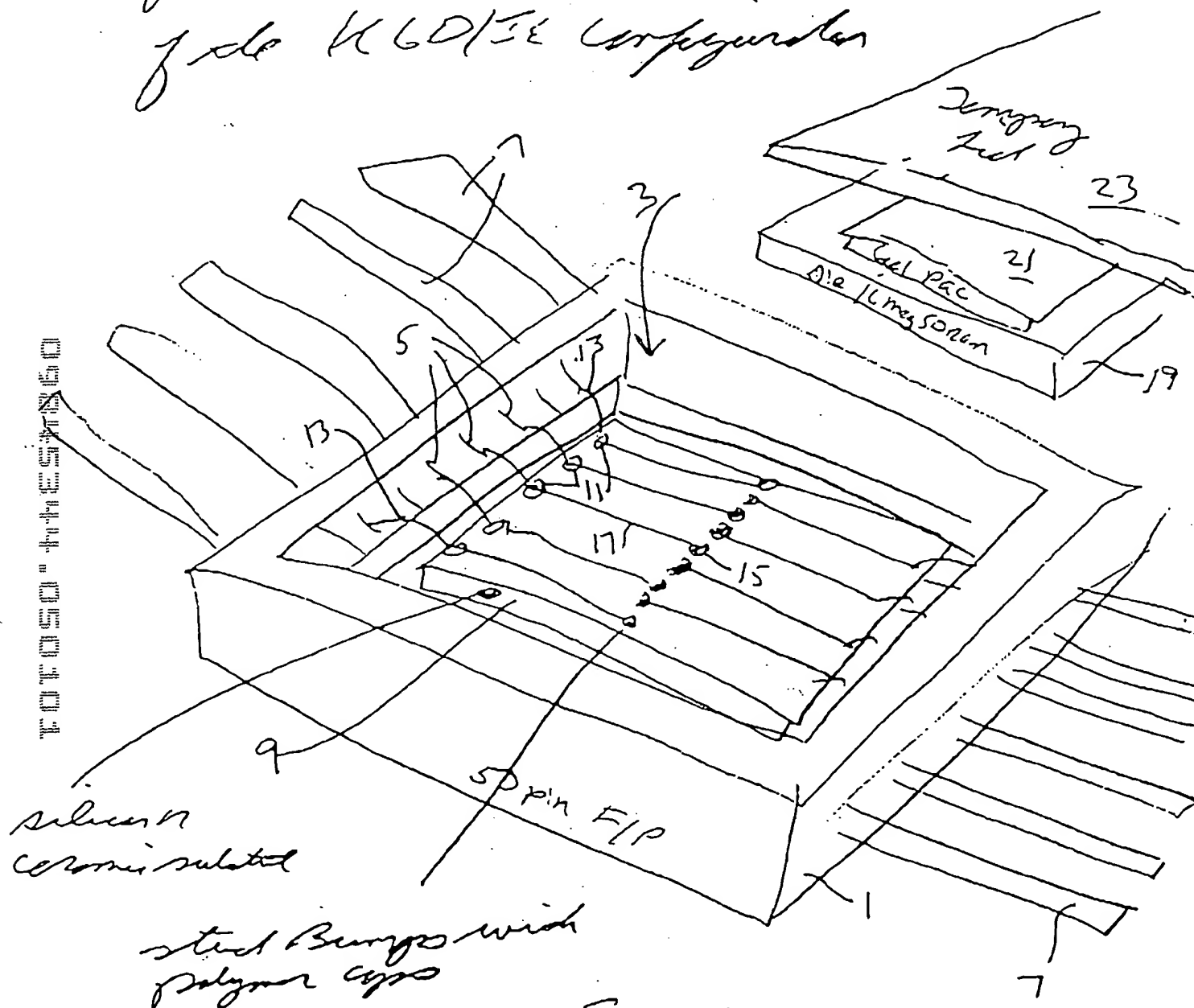


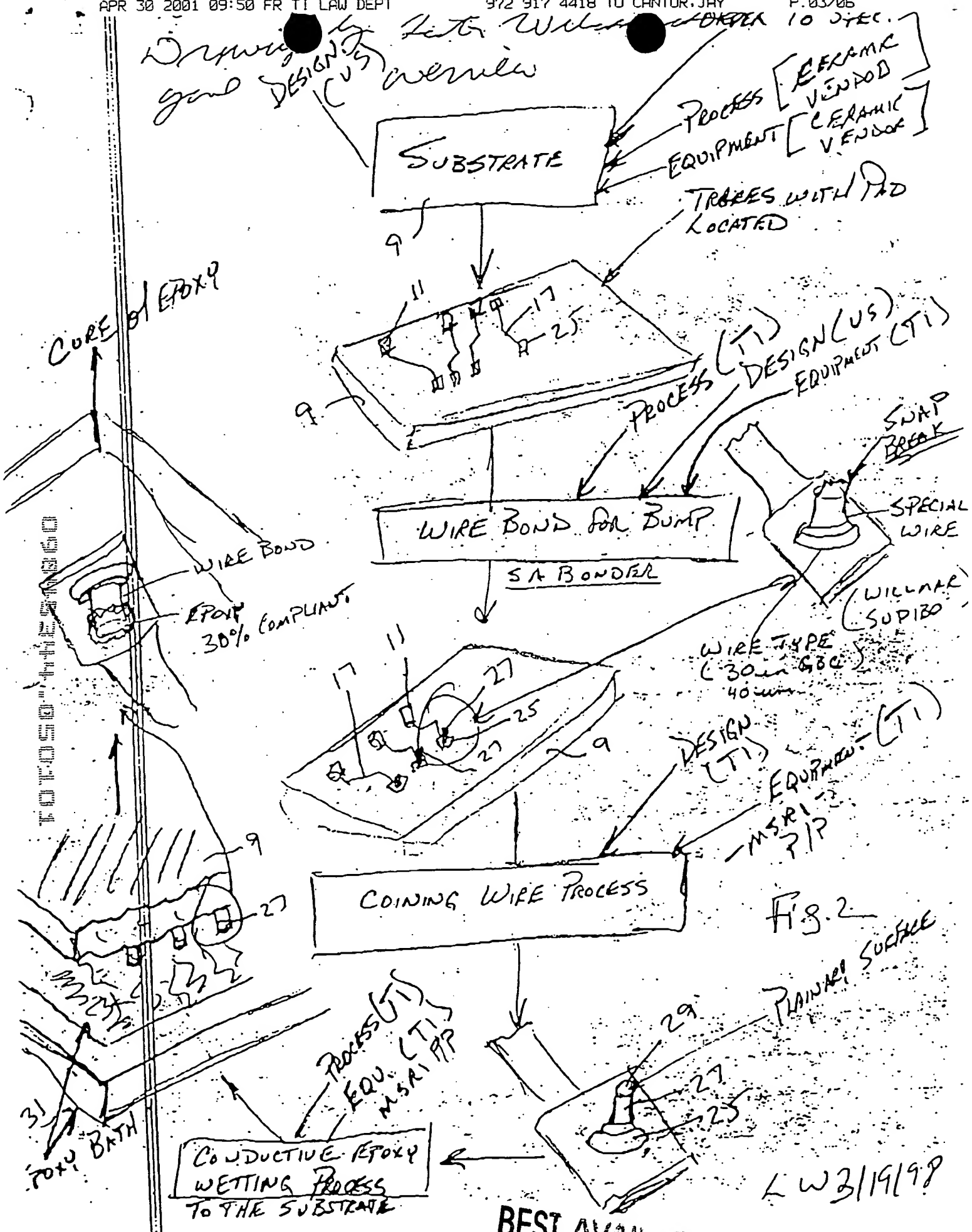
Fig. 1

Assembly member into the circuit
 steel bumps with conductive polymer

RUG 3/19/98

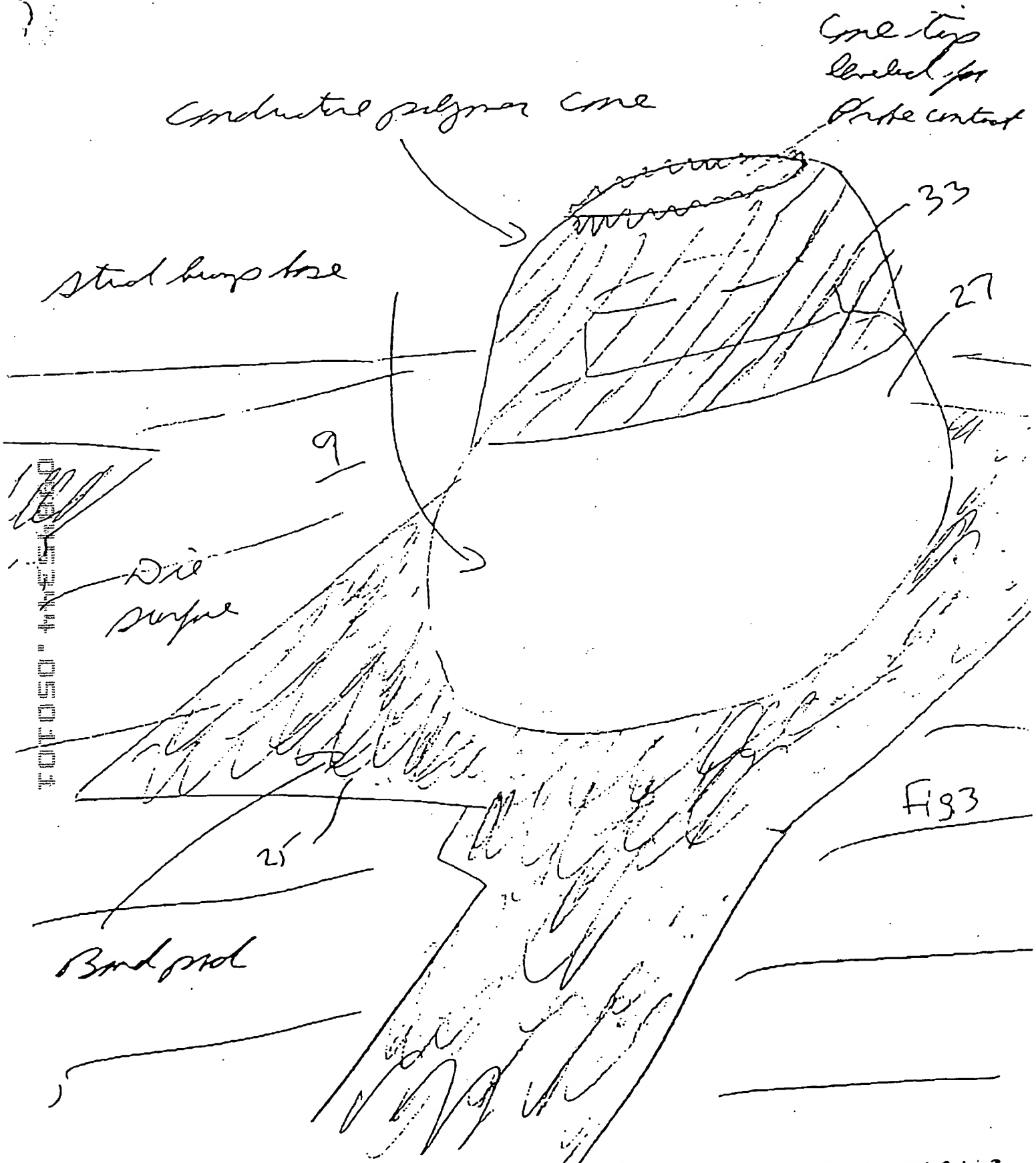
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Drawing by *John Wilson* ORDER 10 SPEC.
good DESIGN (US) review



stud. cone. bump

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3



Final Product for SKB

RAW 3/19/97

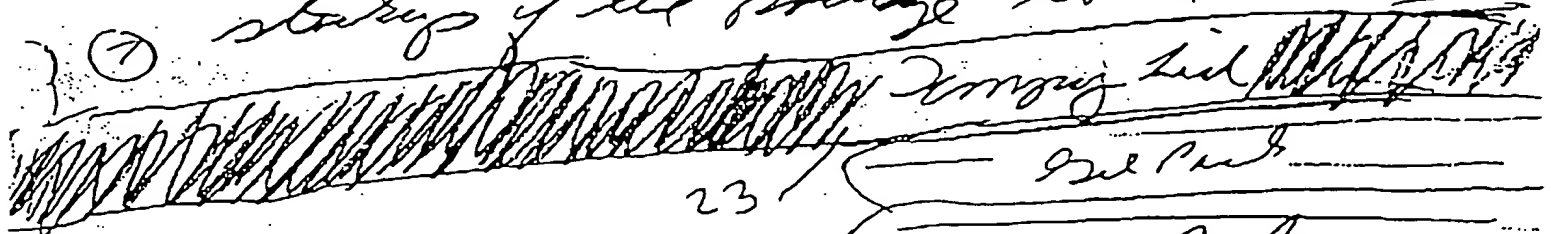
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(11)

Stud 1.0

startup of the package with

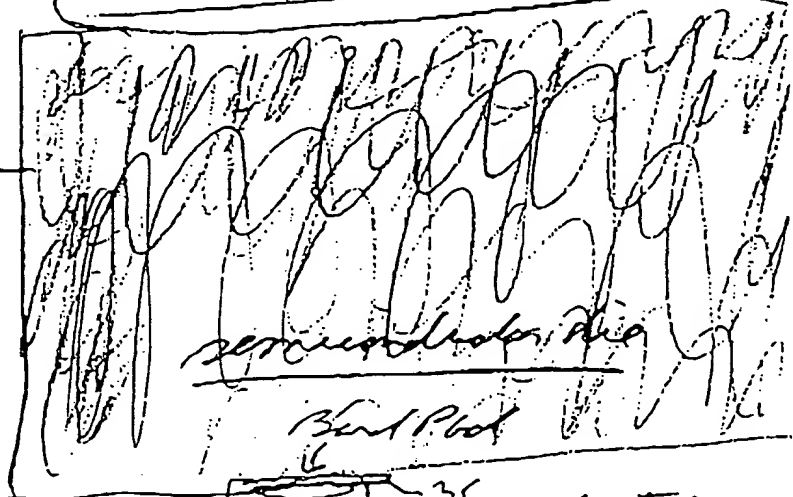
⑦



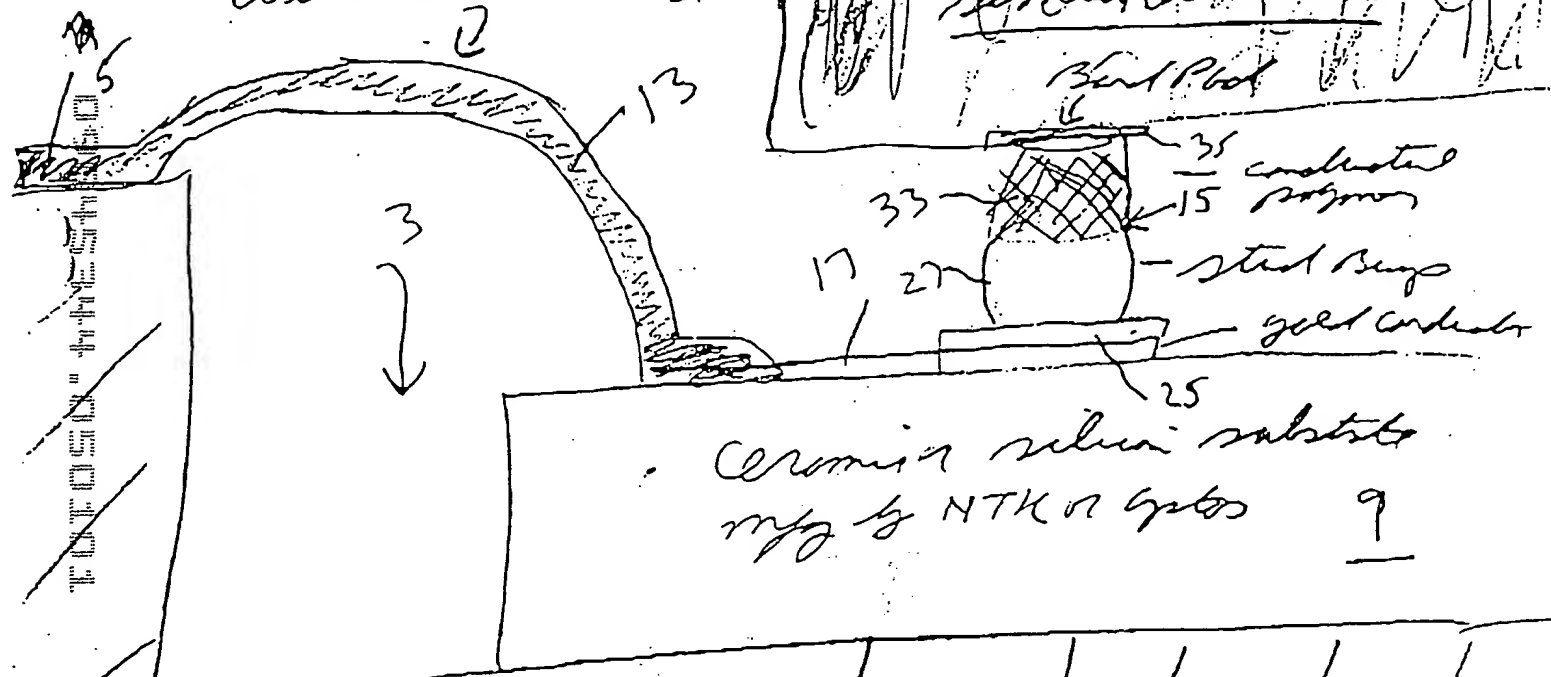
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23
21



Wire Bond to package



Ceramic Pad

Cross section of stud bump Fig. 4
startup with conductive polymer.

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